

IN THE CLAIMS:

Claims 9 have been cancelled. Claims 1-8, and 10-16 have been amended herein. All of the pending claims 1 through 16 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) An encapsulation method for a plurality of electronic devices within a mold cavity in an encapsulation device comprising:
providing a first substrate having a first side, a second side, and at least one electronic component on ~~said the~~ first side of ~~said the~~ first substrate;
providing a second substrate having a first side, second side, and at least one electronic component on ~~said the~~ first side of ~~said the~~ second substrate;
providing upper and lower mating mold plates, each ~~mold plate of said the~~ upper and lower mating mold plates having a mold cavity portion, each ~~said~~ mold cavity portion of ~~said the~~ upper and lower mating mold plates having a feed runner leading thereto from a material supply to ~~said each mold cavity portion~~ and having a vent runner connected thereto for venting ~~said each mold cavity portion~~, ~~said the each~~ mold cavity portions together comprising ~~said the~~ mold cavity portion of ~~said the~~ encapsulation device;
placing ~~said the~~ first substrate having ~~said the~~ at least one electronic component on ~~said the~~ first side thereof and ~~said the~~ second substrate having ~~said the~~ at least one electronic component on ~~said the~~ first side thereof into ~~said the~~ mold cavity portion, ~~said the~~ first substrate and ~~said the~~ second substrate each having ~~said the~~ second side thereof being located between ~~said the~~ upper and lower mating mold plates;
moving ~~said the~~ upper and lower mating mold plates toward each other to form ~~said the~~ mold cavity portion, portions of ~~said the~~ upper mating mold plate engaging portions of ~~said the~~ first surface of ~~said the~~ first substrate and portions of ~~said the~~ lower mating mold plate engaging portions of ~~said the~~ first surface of ~~said the~~ second substrate, ~~said the~~ moving of ~~said the~~ upper and lower mating mold plates toward each other causing ~~said the~~ second

side of ~~said the~~ first substrate and ~~said the~~ second side of ~~said the~~ second substrate to have portions thereof in contact;

injecting a first material into ~~said the~~ upper-mold cavity portion of the upper mating mold plate and a second material into ~~said the~~ lower-mold cavity portion of the lower mating mold plate to separately encapsulate ~~said the~~ at least one electronic component on ~~said the~~ first side of ~~said the~~ first substrate and ~~said the~~ at least one electronic component on ~~said the~~ first side of ~~said the~~ second substrate, ~~said the~~ second material comprising one of the first material ~~or~~ and a similar material; and

removing ~~said the~~ first substrate and ~~said the~~ second substrate from ~~said the~~ upper and lower mating mold plates, ~~said the~~ first substrate and ~~said the~~ second substrate each having at least one encapsulated electronic component on ~~said the~~ first side thereof.

2. (Currently Amended) The method of claim 1, wherein ~~said the~~ injecting ~~said the~~ second material into ~~said the~~ lower-mold cavity portion of the lower mating mold plate comprises injecting a material substantially identical to ~~said the~~ first material.

3. (Currently Amended) The method of claim 1, wherein ~~said the~~ injecting ~~said the~~ second material into ~~said the~~ lower-mold cavity portion of the lower mating mold plate comprises injection of a material substantially different from ~~said the~~ first material.

4. (Currently Amended) The method of claim 1, wherein ~~said the~~ first material and ~~said the~~ second material are injected substantially simultaneously.

5. (Currently Amended) The method of claim 1, wherein ~~said the~~ first material and ~~said the~~ second material are injected at different times.

6. (Currently Amended) The method of claim 1, further comprising cleaning ~~said the~~ second side of each of ~~said the~~ first substrate and ~~said the~~ second substrate.

7. (Currently Amended) The method of claim 1, further comprising curing ~~said the~~ plurality of electronic devices at an elevated curing temperature.

8. (Currently Amended) An encapsulation method for a plurality of electronic devices within a mold cavity of an encapsulation apparatus, ~~said the~~ method comprising:
providing a first substrate having a first side, a second side, and at least one electronic component located on ~~said the~~ first side of ~~said the~~ first substrate;
providing a second substrate having a first side, a second side, and at least one electronic component located on ~~said the~~ first side of ~~said the~~ second substrate;
providing upper and lower mating mold plates, each ~~mold plate of said the~~ upper and lower mating mold plates having a mold cavity portion, each ~~said~~-mold cavity portion of ~~said the~~ upper and lower mating mold plates having a feed runner leading thereto from a material supply to ~~said each mold cavity portion~~ and having a vent runner connected thereto for venting ~~said each mold cavity portion~~, ~~said each mold cavity portions together~~ comprising ~~said the~~ mold cavity of ~~said the~~ encapsulation apparatus;
placing ~~said the~~ first substrate having ~~said the~~ at least one electronic component located on ~~said the~~ first side thereof and ~~said the~~ second substrate having ~~said the~~ at least one electronic component located on ~~said the~~ first side thereof into ~~said the~~ mold cavity, ~~said the~~ second side of ~~said the~~ first substrate and ~~said the~~ second side of ~~said the~~ second substrate placed in a back-to-back orientation between ~~said the~~ upper and lower mating mold plates;
moving ~~said the~~ upper and lower mating mold plates to form ~~said the mold cavity~~ cavity, portions of ~~said the~~ upper mating mold plate engaging portions of ~~said the~~ first side of ~~said the~~ first substrate and portions of ~~said the~~ lower mating mold plate engaging portions of ~~said the~~ first side of ~~said the~~ second substrate and causing ~~said the~~ second side of ~~said the~~ first substrate and ~~said the~~ second side of ~~said the~~ second substrate to have portions thereof in engagement;
injecting a first material into ~~said the~~ mold cavity portion of ~~said the~~ upper mating mold plate and a second material into ~~said the~~ mold cavity portion of ~~said the~~ lower mating mold plate to

separately encapsulate ~~said the~~ at least one electronic component ~~mounted~~ located on ~~said~~ the first side of each of ~~said the~~ first and second substrates of ~~said plurality of electronic devices~~, the second material comprising one of the first material and a similar material;
and
removing ~~said the~~ plurality of electronic devices from ~~said the~~ mold cavity.

9. (Canceled)

10. (Currently Amended) The method of claim 8, wherein the injecting ~~said the~~ second material into ~~said the lower~~ mold cavity portion of the lower mating mold plate comprises ~~injection of~~ injecting a material substantially identical to ~~said the~~ first material.

11. (Currently Amended) The method of claim 8, wherein ~~the~~ injecting ~~said the~~ second material into ~~said the lower~~ mold cavity portion of the lower mating mold plate comprises ~~injection of~~ injecting a material substantially different from ~~said the~~ first material.

12. (Currently Amended) The method of claim 8, wherein ~~said the~~ first material and ~~said the~~ second material are injected substantially simultaneously.

13. (Currently Amended) The method of claim 8, wherein ~~said the~~ first material and ~~said the~~ second material are injected at different times.

14. (Currently Amended) The method of claim 8, further comprising cleaning ~~said~~ the second side of each of ~~said the~~ first substrate and ~~said the~~ second substrate.

15. (Currently Amended) The method of claim 8, further comprising subjecting ~~said~~ the plurality of electronic devices to a curing temperature.

16. (Currently Amended) The method of claim 8, wherein ~~said~~ the second side of each of ~~said~~ the first substrate and ~~said~~ the second substrate of ~~said electronic device~~ includes solder bumps thereon.